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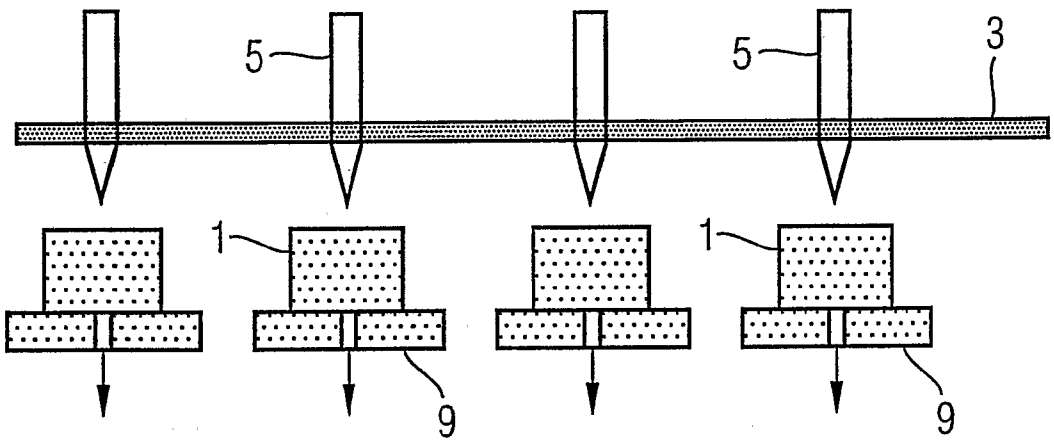
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(54) Title: IMPROVED METHOD AND APPARATUS FOR POSITIONING INTEGRATED CIRCUITS ON DIE PADS



(57) Abstract: A foil (3) carrying a plurality of integrated circuits (1) is positioned so that the integrated circuits (1) are in register with the die pads (9) of a lead frame. The integrated circuits (1) are transfered to the die pads (9) by a single movement. The single movement can be produced by pushing the integrated circuits (1) simultaneously off the foil (3) and onto the die pads (9) using push needles (5) which pass through the foil (3). Thus the present invention makes it possible to dramatically increase the rate at which integrated circuits (1) are positioned on the die pads (9) of lead frames.

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